



CLEANALLOY - An alloy for flow soldering printed circuit boards refined and processed to the highest standards of purity. Produced from very high quality, virgin metals and smelted under a nitrogen atmosphere. The manufacturing process minimises the formation of superficial oxides during production. When used, *CLEANALLOY* stays bright and soldering defects such as bridges, flags and spikes are reduced to an absolute minimum. Maximum advantage can be gained from *CLEANALLOY* bar solder when used with flow solder machines having a "nitrogen blanket" facility although increased performance will be gained in conventional "open atmosphere" types.

This alloy exceeds the requirements laid down in the Standards:
NFC 90550, DIN 1707, B.S.219 Code AP and BS EN Alloy No. 1a.

Chemical Characteristics

Tin and lead from first melting:

Amount of Tin:	62.4% to 63.6 %
Amount of Lead:	Remainder
Tin and lead from first melting purity:	>99.95%.

Chart of maximum impurities, example:

Cu	Ag	Cd	Sb	Bi
<0.003%	<0.003%	<0.001%	<0.01%	<0.01%

Fe	Zn	Al	As	S
<0.01%	<0.001%	<0.001%	<0.01%	<0.001%

Cl	P	others
<0.001%	<0.001%	<0.05%

Incorporated flux: **Synthetic Halide Free:**
 S45V as approved by HSE Laboratory
 Compatible with most dispensers.

Physical Characteristics, standard:

*ALLOY Sn63 Pb37 Eutectic	
Melting point	Solidus to Liquidus @ 183°C Eutectic
Working temperature	230 to 260°C. Optimum @ 240°C
Specific weight	8.4

Supplied As

Bars: Extruded ~ 900gm Bars in cartons of 24
 (Exact Tare weight stated on carton).

Sticks: 250g in Cartons of 25 Kgs.

Granules: Containers of 20 Kgs.

Ingots: Approximate weight 3.9 Kgs

Wire: On spools of 250gms - 20 Kgs. Drum
 packs are also available.

Storage

Original packaging, at an average temperature of
 20°C.